NOTE 5

E1

7X b

TOP VIEW

SIDE VIEW

0.10 C

⊕ 0.12 M C A-B D

□ 0.10 | C | A-B |

0.10 \triangle

C SEATING PLANE

С

7



0.20 С

NOTE 5 B

SOIC8 MISSING PIN 3 CASE 751EV ISSUE O

DETAIL A

END VIEW

DETAIL A

DATE 19 SEP 2017

NOTES:

NOTE 6 Α1

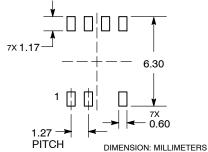
C SEATING PLANE

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10mm IN EXCESS OF MAXIMUM MATERIAL
- 4. DIMENSIONS D & E1 DOES NOT INCLUDE MOLD DIMENSIONS D & E1 DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM F.

 DATUMS A AND B ARE TO BE DETERMINED AT
- DATUM F.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

	MILLIMETERS			
DIM	MIN	MAX		
Α	1.35	1.75		
A1	0.10	0.25		
b	0.33	0.51		
С	0.19	0.25		
D	4.80	5.00		
E	5.80	6.20		
E1	3.80	4.00		
е	1.27 BSC			
L	0.40	1.27		
L2	0.25 BSC			
M	0° 8°			

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

= Assembly Location Α

L = Wafer Lot Υ = Year = Work Week W

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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